

# LOW-PROFILE COMPRESSION INTERPOSER

(1.00 mm) .0394" PITCH • GMI SERIES

## SPECIFICATIONS

**Insulator Material:**  
Black LCP  
**Contact Material:**  
Copper Alloy  
**Plating:**  
Au or 50 μ" (1.27 μm) Ni  
**Current Rating:**  
.89 A per pin  
(10 pins powered)

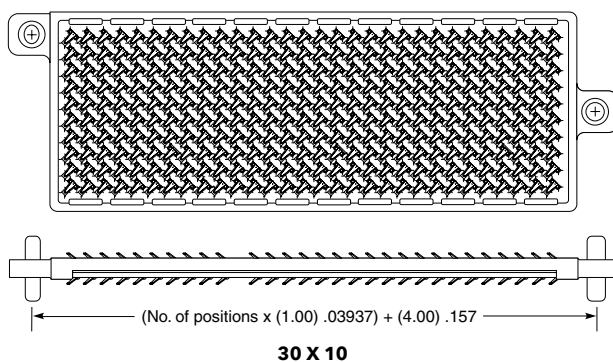
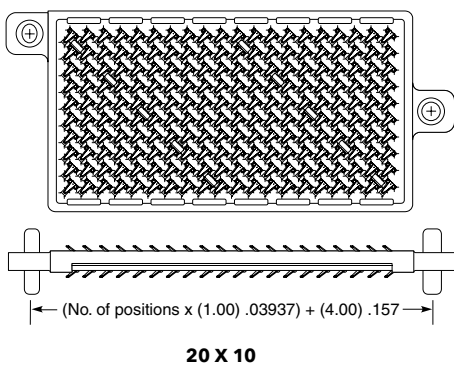
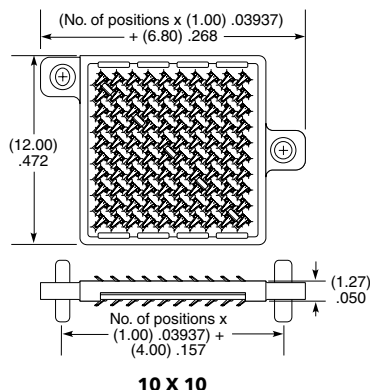
GMI	POSITIONS PER ROW	STYLE	BOARD SPACING	PLATING OPTION	ROWS
	-10, -20, -30	-2 = Dual Compression	-1.27 = (1.27 mm) .050" Board Space	-G = 10 μ" (0.25 μm) Gold on contact area	-10 = Ten Rows

## PROCESSING

**Lead-Free Solderable:**  
Yes  
**SMT Lead Complanarity:**  
(0.05 mm) .002" (10-20)\*  
(0.08 mm) .003" (30)\*  
\*(.004" stencil solution may be available)



GMI Series is an ideal low-cost solution for board stacking, module-to-board or LGA interface



**Notes:**  
Some lengths, styles and options are non-standard, non-returnable